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# SEMICONDUCTOR®

FAIRCHILD

## **IRFS250B** 200V N-Channel MOSFET

## **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

## **Features**

• 21.3A, 200V,  $R_{DS(on)} = 0.085\Omega @V_{GS} = 10 V$ • Low gate charge (typical 95 nC)

D

- Low Crss (typical 75 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter Drain-Source Voltage		IRFS250B	Units V	
V <sub>DSS</sub>			200		
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	°C)	21.3	Α	
	- Continuous (T <sub>C</sub> = 100	)°C)	13.5	Α	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	85	Α	
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	600	mJ	
AR	Avalanche Current	(Note 1)	21.3	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	9.0	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
P <sub>D</sub>	Power Dissipation ( $T_C = 25^{\circ}C$ )		90	W	
	- Derate above 25°C		0.72	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

## **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.38	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_{D} = 250 \mu A$		200			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, Referenced to 25°C			0.2		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$			10	μA	
		V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C				100	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{\text{D}} = 10.65 \text{ A}$			0.071	0.085	Ω
9fs	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 10.65 A (Note 4)			22		S
C <sub>iss</sub> C <sub>oss</sub>	ic Characteristics Input Capacitance Output Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz			2600 330	3400 430	pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance				75	100	pF
Switchi	ing Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 32 A,			30	70	ns
t <sub>r</sub>	Turn-On Rise Time	$R_{G} = 25 \Omega$			240	490	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	-			295	600	ns
t <sub>f</sub>	Turn-Off Fall Time	٩)	lote 4, 5)		195	400	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 160 V, I <sub>D</sub> = 32 A,			95	123	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V			13		nC
Q <sub>gd</sub>	Gate-Drain Charge	٩)	lote 4, 5)		43		nC
Drain-S	ource Diode Characteristics ar	nd Maximum Ratings					
I <sub>S</sub>	Maximum Continuous Drain-Source Dic	de Forward Current				21.3	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	Forward Current				85	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 21.3 A$				1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{S} = 32 A,$			220		ns
-			(Noto 4)			1	

 $dI_{F} \, / \, dt = 100 \, \, \text{A} / \mu \text{s}$ 

(Note 4)

1.89

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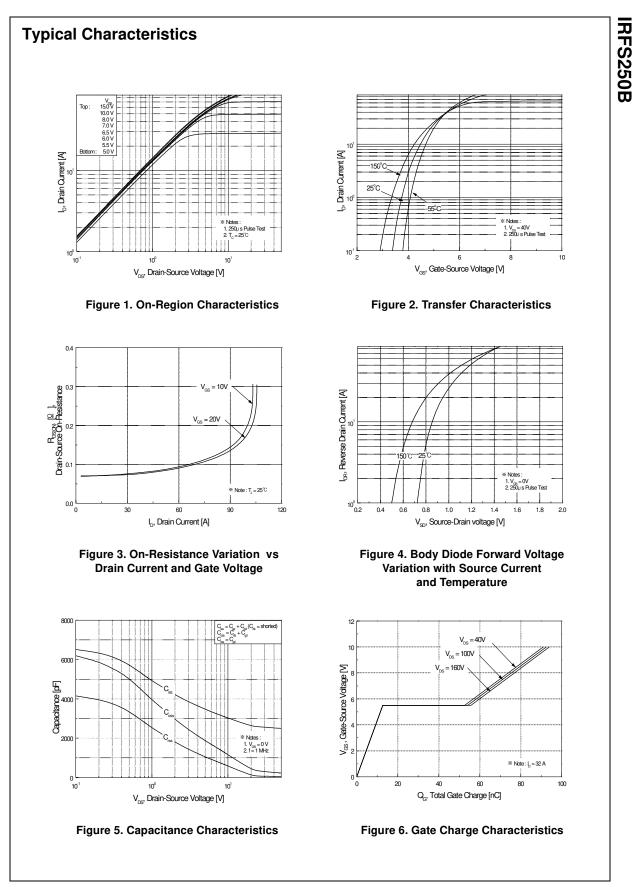
μC

Q<sub>rr</sub>

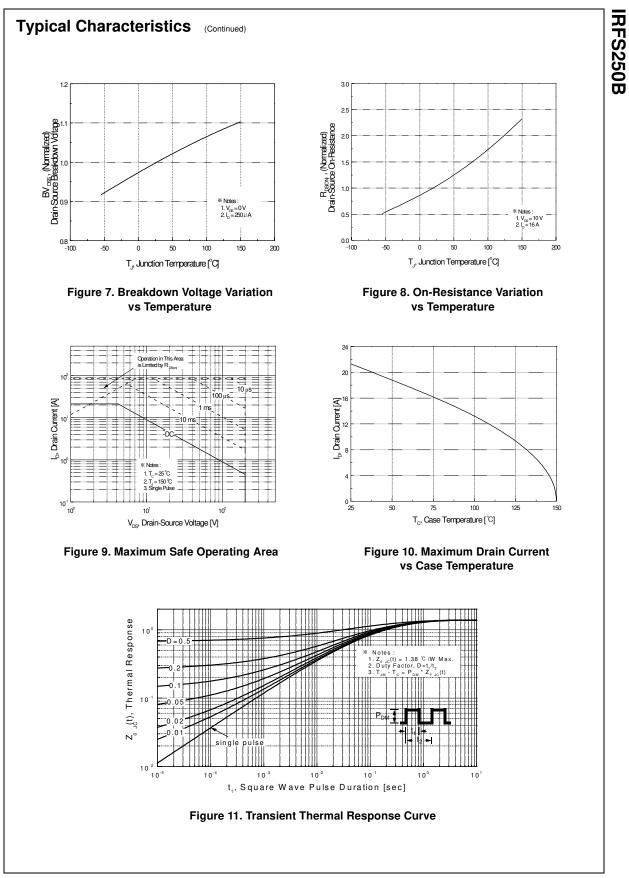
Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 1.98mH, I<sub>AS</sub> = 21.3A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  32A, di/dt  $\leq$  300A/µs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

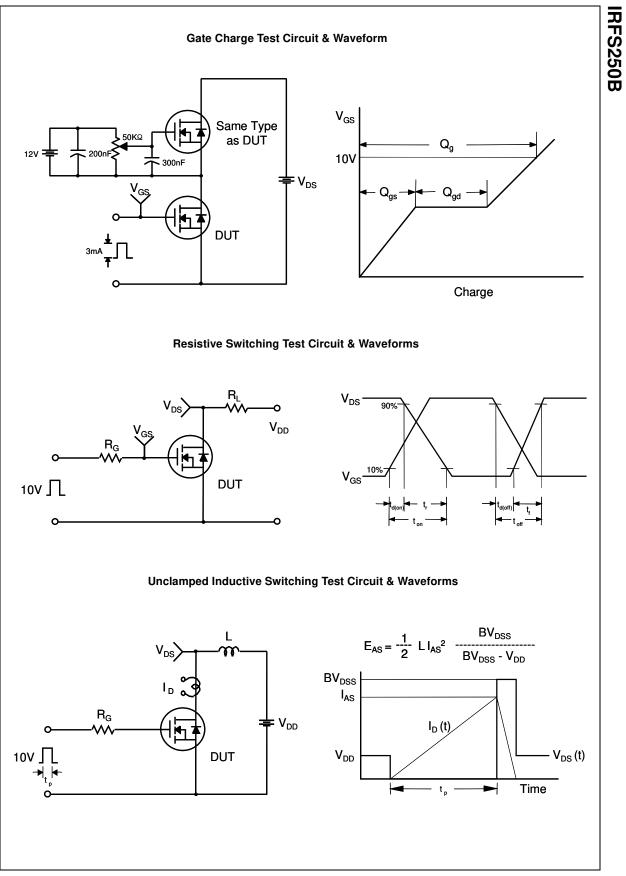
Reverse Recovery Charge

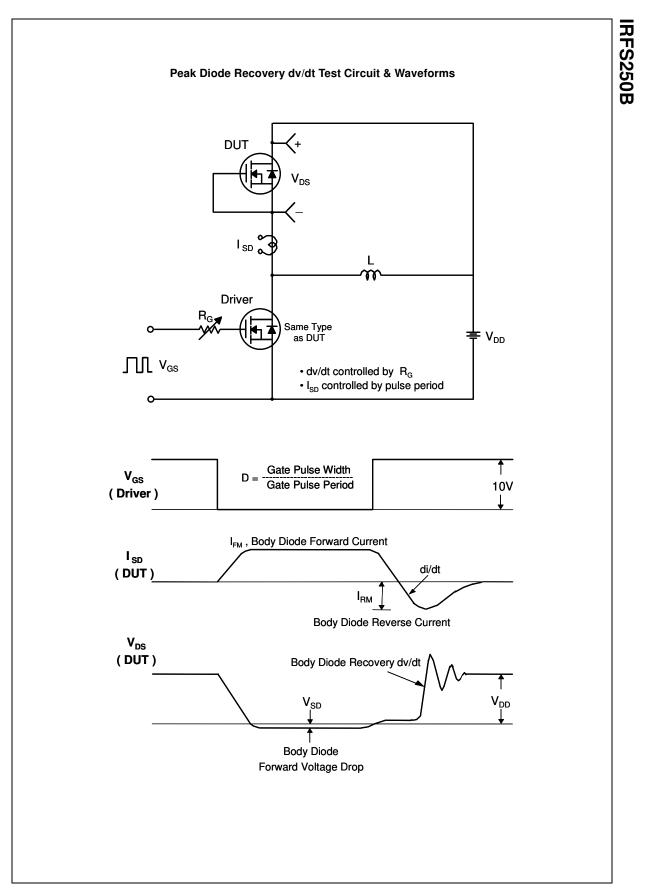
**IRFS250B** 

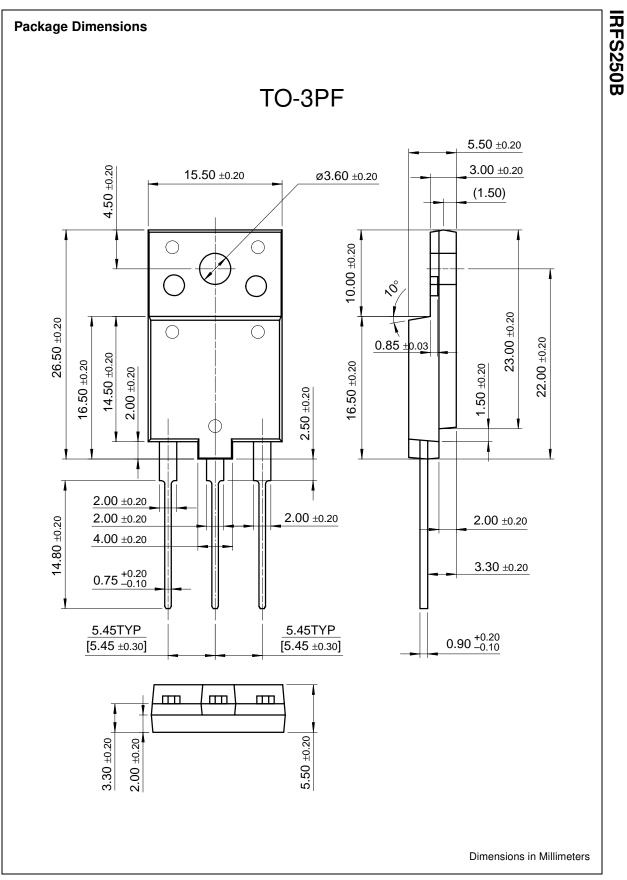


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#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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## IRFS250B

200V N-Channel B-FET / Substitute of IRFS250 & IRFS250A

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Product	Product status	Pb-free Status	Package type	Leads	Packing method	Package Marking Convention**
IRFS250B_FP001	Not recommended for new designs	۲	TO-3PF	3	RAIL	Line 1: <b>\$Y</b> (Fairchild logo) & <b>Z</b> (Asm. Plant Code) & <b>4</b> (4-Digit Date Code) Line 2: IRFS Line 3: 250B

Indicates product with Pb-free second-level interconnect. For more information click here.

Package marking information for product IRFS250B is available. Click here for more information.

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## **Qualification Support**

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